

# **FMI12N50E**

**FUJI POWER MOSFET** 

# Super FAP-E<sup>3</sup> series

# **N-CHANNEL SILICON POWER MOSFET**

#### Features

Maintains both low power loss and low noise Lower  $R_{DS}(on)$  characteristic More controllable switching dv/dt by gate resistance Smaller  $V_{GS}$  ringing waveform during switching Narrow band of the gate threshold voltage  $(3.0\pm0.5V)$  High avalanche durability

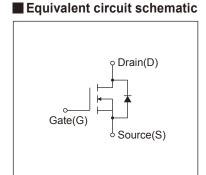
## Applications

Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

# ■ Maximum Ratings and Characteristics

# ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

# Outline Drawings [mm] T-Pack(L) 10 3 4 5 19.2 1.219.2 1.219.2 1.219.2 2.319.2



Description	Symbol	Characteristics	Unit	Remarks
Dunin Sauras Valtaria	V <sub>DS</sub>	500	V	
Drain-Source Voltage	V <sub>DSX</sub>	500	V	V <sub>GS</sub> = -30V
Continuous Drain Current	Io	±12	A	
Pulsed Drain Current	IDP	±48	A	
Gate-Source Voltage	V <sub>G</sub> s	±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	IAR	12	A	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	400	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	16.5	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	6.5	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Mayimum Bawar Biocinetian	PD	1.67	W	Ta=25°C
Maximum Power Dissipation		165	VV	Tc=25°C
Oneveting and Stavens Temperature vanue	Tch	150	°C	
Operating and Storage Temperature range	Tstg	-55 to +150	°C	
Isolation Voltage	Viso	2	kVrms	t = 60sec, f = 60Hz

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit	
Drain-Source Breakdown Voltage	BVDSS	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		500	-	-	V	
Gate Threshold Voltage	V <sub>GS</sub> (th)	In=250µA, Vos=Vos	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		3.0	3.5	V	
Zero Gate Voltage Drain Current		V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	Tch=25°C	-	-	25	μA	
	Inss	V <sub>DS</sub> =400V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250		
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		10	100	nA	
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =6A, V <sub>GS</sub> =10V		-	0.444	0.52	Ω	
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =6A, V <sub>DS</sub> =25V		6.5	13	-	S	
Input Capacitance	Ciss	V <sub>DS</sub> =25V		-	1600	2400	pF	
Output Capacitance	Coss	V <sub>GS</sub> =0V	V <sub>GS</sub> =0V		160	240		
Reverse Transfer Capacitance	Crss	f=1MHz		-	11.5	17.5	]	
Turn-On Time	td(on)	V <sub>cc</sub> =300V V <sub>cs</sub> =10V I <sub>D</sub> =6A		-	20	30	ns	
	tr			-	9	13.5		
Turn-Off Time	td(off)			-	100	150		
	tf	R <sub>G</sub> =15Ω		-	18	27	1	
Total Gate Charge	QG	Vcc=300V	V <sub>cc</sub> =300V I <sub>D</sub> =12A		47	70.5	nC	
Gate-Source Charge	Qgs	I <sub>D</sub> =12A			10.5	16		
Gate-Drain Charge	Q <sub>GD</sub>	V <sub>GS</sub> =10V		-	14	21		
Avalanche Capability	lav	L=2.12mH, Tch=25°C	L=2.12mH, Tch=25°C		-	-	А	
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =12A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°0	I <sub>F</sub> =12A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		0.88	1.32	V	
Reverse Recovery Time	trr	I <sub>F</sub> =12A, V <sub>GS</sub> =0V		-	0.36	-	μs	
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	4.1	-	μC	

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to Case			0.758	°C/W
	Rth (ch-a)	Channel to Ambient			75.0	°C/W

Note \*1 : Tch≤150°C

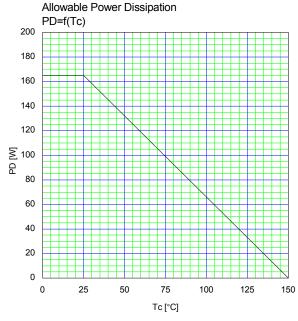
Note \*2 : Stating Tch=25°C, Ias=5A, L=29.2mH, Vcc=50V, Re=50Ω
Eas limited by maximum channel temperature and avalanche current.
See to 'Avalanche Energy' graph.

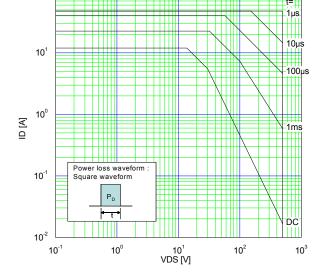
Note \*3 : Repetitive rating : Pulse width limited by maximum channel temperature.

See to the 'Transient Themal impeadance' graph.

Note \*4 : Ir≤-lp, -di/dt=100A/µs, Vcc≤BVbss, Tch≤150°C.

Note \*5 : Ir≤-lp, dv/dt=6.5kV/µs, Vcc≤BVbss, Tch≤150°C.

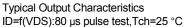


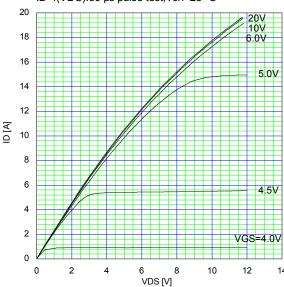


Safe Operating Area

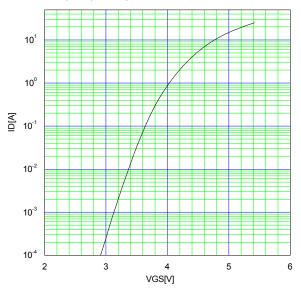
10<sup>2</sup>

ID=f(VDS):Duty=0(Single pulse),Tc=25 °c

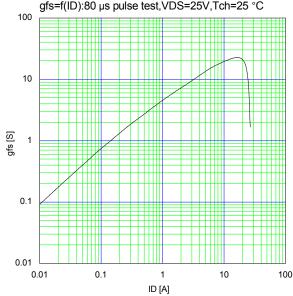




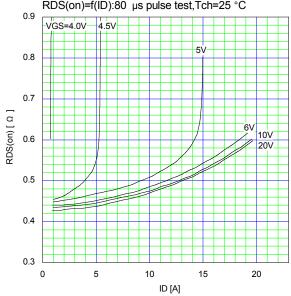
Typical Transfer Characteristic ID=f(VGS):80 µs pulse test,VDS=25V,Tch=25 °C



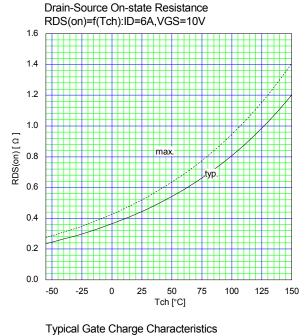
Typical Transconductance gfs=f(ID):80 µs pulse test,VDS=25V,Tch=25 °C

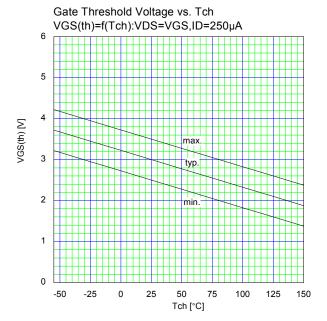


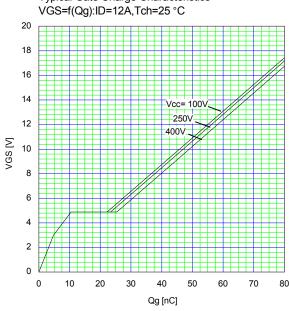
Typical Drain-Source on-state Resistance RDS(on)=f(ID):80 µs pulse test,Tch=25 °C

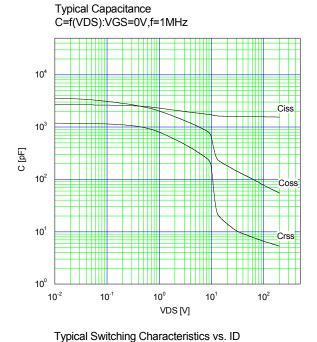


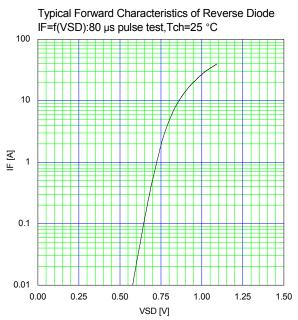
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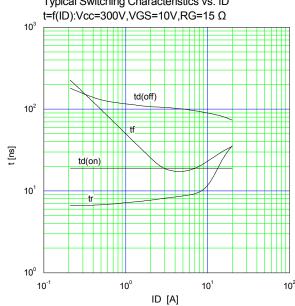


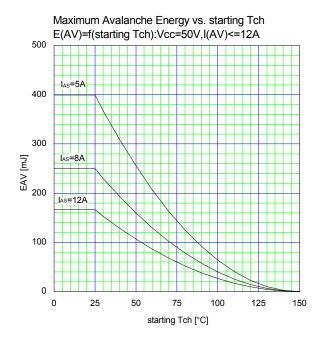


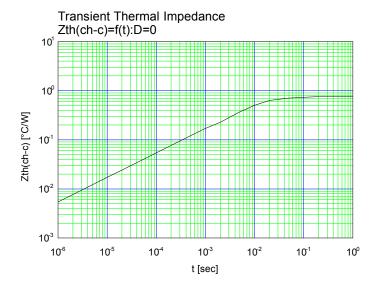












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